

Appl. No. 10/761,690

Amdt. dated November 23, 2005

Reply to Office action of August 23, 2005

10. (original) The system of Claim 9 wherein said pivoting member is a rotating vacuum coupling.

11. (original) The system of Claim 1 wherein said horizontal member is a solder ball mount.

12-18. (canceled)

19. (previously presented) A system for depositing solder onto a substrate, comprising:

a horizontal member adapted to hold said solder;

a receiving member having a portion adapted to receive said substrate opposite said horizontal member; and a portion adapted to rotate independently with respect to the horizontal member; said rotatable receiving member comprises a base, a vertical member removably coupled to said base defining a T-shaped structure, said vertical member being adapted to act as an air conduit for selectively holding said substrate on said base;

a contact member having protruding portions adapted to selectively contact a substantially planar surface of the substrate on said receiving member, said contact member being positioned between said horizontal member and said receiving member,

whereby said receiving member and said contact member functionally cooperate to hold said received substrate in a substantially planar position with respect to said horizontal member before and after said solder is deposited thereon.

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